

ABSTRACT OF THE DISCLOSURE

In order to imprint wafer-identifying information on a wafer on which a plurality of thin-film devices are formed in a batch, utilizing a patterned resist layer, an exposure apparatus exposes a resist layer formed on the wafer to light for forming a latent image of the wafer-identifying information. The exposure apparatus allows a mask storage controller and a mask transfer device to select a mask, on which the pattern of a numeral or symbol to be imprinted is drawn, for each digit of the wafer-identifying information and carries out exposure. The exposure apparatus also allows a mask shift controller to change the positional relationship between the wafer and the mask for each digit of the wafer-identifying information so that the numeral or symbol of each digit of the wafer-identifying information is imprinted at a mutually different position.